



PK407 (v1.1) April 9, 2012

# 100% Material Declaration Data Sheet CSG225 for Spartan®-6 FPGAs

**Average Weight: 0.3830 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.012563</b>	<b>3.280</b>
	Silicon	7440-21-3	100.00		0.012563	
<b>Die Attach Material</b>					<b>0.002453</b>	<b>0.640</b>
	Silver	7440-22-4	77.50		0.001901	
	Bismaleimide monomer	Trade Secret	15.00		0.000368	
	Acrylate monomer	Trade Secret	7.50		0.000184	
<b>Mold Compound</b>					<b>0.169140</b>	<b>44.162</b>
	Solid Epoxy Resin	Trade Secret	11.00		0.018605	
	Phenol Resin	Trade Secret	11.00		0.018605	
	Fused Silica	60676-86-0	62.40		0.105543	
	Metal Hydroxide	Trade Secret	15.05		0.025456	
	Carbon Black	1333-86-4	0.55		0.000930	
<b>Gold Wire</b>					<b>0.002453</b>	<b>0.640</b>
	Gold	7440-57-5	99.05		0.002430	
	Palladium	7440-05-3	0.95		0.000023	
	Calcium	7440-70-2	0.00		0.000000	
<b>Solder Balls</b>					<b>0.063453</b>	<b>16.567</b>
	Tin	7440-31-5	96.50		0.061232	
	Silver	7440-22-4	3.00		0.001904	
	Copper	7440-50-8	0.50		0.000317	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					<b>0.132938</b>	<b>34.710</b>
	Copper	7440-50-8	9.99		0.013281	
	Nickel	7440-02-0	3.52		0.004679	
	Gold	7440-57-5	4.21		0.005597	
	Glass fiber (GF)	65997-17-3	14.92		0.019834	
	Non-halogen flame retardant	1675-54-3	0.06		0.000080	
	BT (core)	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-38-2	42.41		0.056379	
	Solder mask	13676-54-5 25722-66-1 147-14-8 7727-43-7 61790-53-2 14807-96-6 461-58-5 7723-14-0	24.89		0.033088	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/31/10	1.0	Initial Xilinx release.
04/09/12	1.1	Component Weight update.

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